

BPM TGF Daughter Card
Rev 1.1, Oct 18 2004



Layer Stackup:

- 1) Component Side
- 2) Power Plane
- 3) Ground Plane
- 4) Solder Side

SMT Pad Count:

Top: 0
Bottom: 24

ThruHole Count:82

Job Spec's

Material: FR-4
Material Thickness: 0.063"
Copper Weight: 1/2oz Inner/Outer Layers
Finnish/Plating: Tin-Lead
SolderMask Type: LPI
SilkScreen Layers: Top & Bottom
Min. Trace Width: 6mil
Min. Trace Spacing: 6mil
Smallest Hole Size: 12mil
Largest Hole Size: 120mil
Job Turn Around Time: 10 Day Turn
Job Qnt.: 38 Pieces

Controlled Impedence:

All Bot Layer 10mil traces are to be
50 ohms to Top layer GND plane.
6mil distance between solder side
and ground plane.